

C0603X332F3GECTU

Aliases (C0603X332F3GEC7867)

ESD SMD Comm COG, Ceramic, 3,300 pF, 1%, 25 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0.4 mm, 0603 / 1608



Click [here](#) for the 3D model.

General Information

Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Flexible Termination
Marking	No
Typical Component Weight	4.6 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	3,300 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	1%
Voltage DC	25 VDC
ESD Level per AEC-Q200	16,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Dimensions

L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
T	0.8mm +/-0.15mm
S	0.4mm MIN
B	0.45mm +/-0.15mm
Case Code (EIA / mm)	0603 / 1608

Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

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